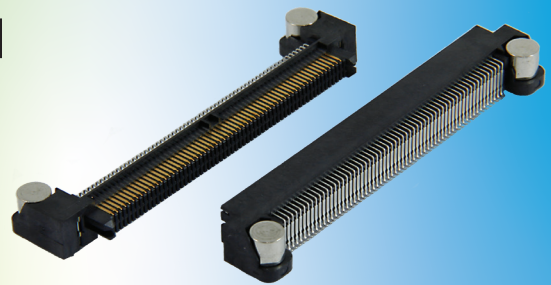




HSER™

Series 2386



High Speed Board-to-Board

Specification

Insulator Material:
Housing: Black Liquid Crystal Polymer, UL94V-0

Signal Contact:
Contact Material: Phosphor Bronze
Contact Plating: Au over 50 μ" (1.27μm) Ni
Solder Tail Plating: Matte Tin over 50 μ" (1.27μm) Ni

Counterweight Material:
Brass

Latch Material:
Brass

Mounting Type:
SMD

Current Rating:
1.4 A / pin (6 adjacent powered pins)

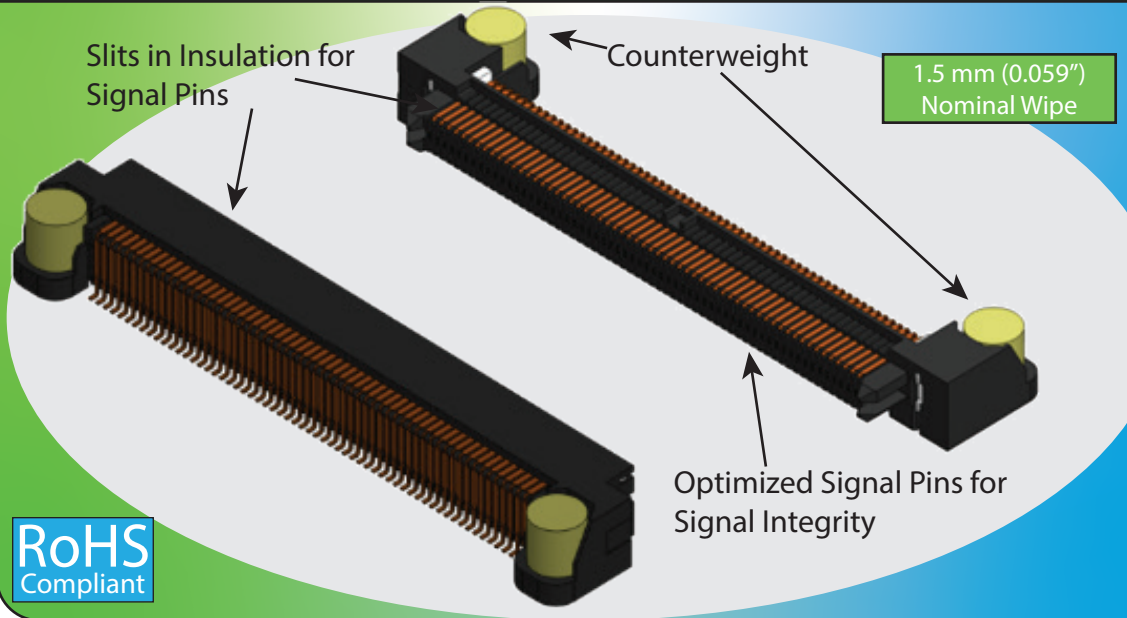
Operating Temperature:
-55°C ~ +125°C

Voltage Rating:
900V AC

Mating Cycles:
500

Insertion Force:
36N max.

Extraction Force:
6N min.



HSER™ Series	
Pitch	0.80 mm (.0315")
Pin Count	120
Profile Height	6.25 mm (0.246")

High Speed Performance

28 Gbps

Differences in SI Testing Boards Result in Differences in Measured Speed.

Options

Contact Plating:
10μ" Gold
30μ" Gold

Male Signal Pin Length:
0.65 mm — Ground Pin Length is 0.65 mm

Packaging:
Tape & Reel

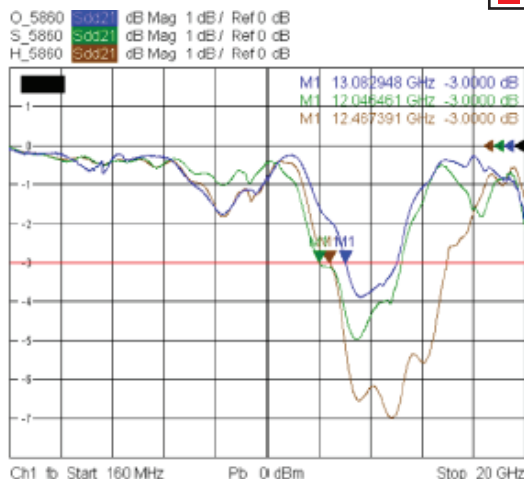
Other:
Pick & Place Mylar Pad
Lock
Guide Pin
Metal Post
Extended Guide Post (Female Only)

* Refer to Product Drawings for Specific Details

Product Specification, Drawings, Certifications, Test Reports and SI Report Available Upon Request

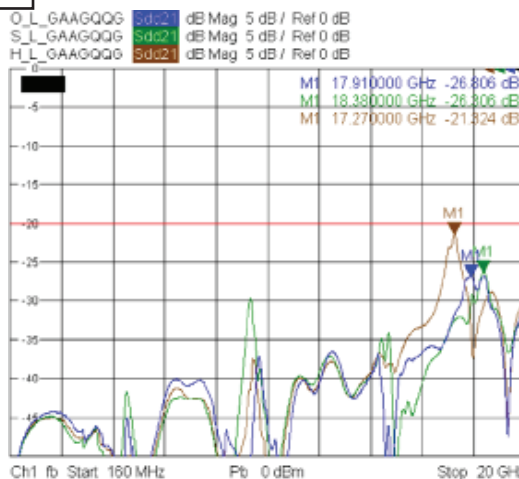
SI Report

Differential Pair Insertion Loss GSSG



Loss	Oupiin	Competitor 1	Competitor 2
-3dB	13.08 GHz	12.04 GHz	12.46 GHz

Differential Pair Near End Crosstalk GAAGQQG



Loss	Oupiin	Competitor 1	Competitor 2
Standard Value	17.91 GHz	18.38 GHz	17.27 GHz

Standard value: ≤ -20dB to 20 GHz

